

MKP Film Capacitor

Material Data Sheet

Product Class	MKP Motor run round B32330x / B32332x	
Date	18/11/2019	
IMDS ID if available	NA	
Version	5.02.1a (03/2019)	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt-%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Thermoplastic	2A	PP	100	9003-07-0	35	
	Light Metal	1B	AL	6	7429-90-5	9.8	
	Heavy Metal	1C	Zn	94	7440-66-6		
Encapsulation	Light Metal	2B	Al	100	7429-90-5	14.9	
	Thermoplastic	2A	Polyamide 66 or	100 or	32131-17-2 or	12.6	
	Thermoplastic	2A	Polyamide 6	35	25038-54-4		
	Filler Material	5A	Fiber glass	30	65997-17-3		
	Flame Retardant	Not available	Brominated flame retardants	25	Not available		
	Inorganic solid	4A	Sb2O3	10	1309-64-4		
Elastomer	2C	Silicon	90	68083-18-1	0.6		
		Silica	10	7631-86-9			
Duromer	2D	Polyurathan	100	Not available	23.2		
Termination	Iron & Steel	1A	Fe	94	7439-89-6	2	
	Heavy Metal	1C	Cu	4	7440-50-8		
	Heavy Metal	1C	Sn	2	7440-31-5		
	Heavy Metal	1C	Sn	99.3	7440-31-5	1.2	
			Cu	0.7	7440-50-8		
Mounting Part	Iron & Steel	1A	Fe	92	7439-89-6	0.7	
	Heavy Metal	1C	Zn	8	7440-66-6		
Sum in total:						100	

sizes [dxh]	weight range [g]	sizes [dxh]	weight range [g]	sizes [dxh]	weight range [g]
30 x 52	62	40 x 103	154	50 x 80	177
30 x 68	65	40 x 130	179	50 x 92	209
30 x 73	74	45 x 78	146	50 x 105	232
30 x 93	86	45 x 83	156	50 x 132	280
40 x 68	99	45 x 103	193	53 x 80	194
40 x 78	113	45 x 130	232	53 x 105	302

Not part of a Product Class		Important remarks: 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE
Contact	M. Surendrababu	
Division	CAP FILM, AC, R&D	
Address	TDK India Pvt. Ltd. E 22/25, 25/1, MIDC, Satpur, Nashik, INDIA -422007 Tel: +91 253 2205 210 mailto:lucia_cabo@epcos.com	
*) others: (not declarable or prohibited substances acc. GADSL) **) typical mass percentage of substance		

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (valid not valid)

- no exemptions;**
- Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;
- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- Other Exemption than above